BLF6G10-200RN; BLF6G10LS-200RN Power LDMOS transistor

Rev. 3 — 1 September 2015

AMPLEON

Product profile

1.1 General description

200 W LDMOS power transistor for base station applications at frequencies from 700 MHz to 1000 MHz.

Table 1. Typical performance

Typical RF performance at $T_{case} = 25$ °C in a class-AB production test circuit.

Mode of operation	f	V _{DS}	P _{L(AV)}	Gp	η_{D}	ACPR	
	(MHz)	(V)	(W)	(dB)	(%)	(dBc)	
2-carrier W-CDMA	869 to 894	28	40	20	28.5	_39 <u>[1]</u>	

^[1] Test signal: 3GPP; test model 1; 64 DPCH; PAR = 7.5 dB at 0.01 % probability on CCDF per carrier; carrier spacing 5 MHz.

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Therefore care should be taken during transport and handling.

1.2 Features

- Typical 2-carrier W-CDMA performance at frequencies of 869 MHz and 894 MHz, a supply voltage of 28 V and an I_{Dq} of 1400 mA:
 - Average output power = 40 W
 - ◆ Power gain = 20 dB
 - ◆ Efficiency = 28.5 %
 - ◆ ACPR = -39 dBc
- Easy power control
- Integrated ESD protection
- Enhanced ruggedness
- High efficiency
- Excellent thermal stability
- Designed for broadband operation (700 MHz to 1000 MHz)
- Internally matched for ease of use
- Compliant to Directive 2002/95/EC, regarding restriction of hazardous substances (RoHS)

1.3 Applications

■ RF power amplifiers for GSM, GSM EDGE, W-CDMA and CDMA base stations and multicarrier applications in the 700 MHz to 1000 MHz frequency range.

2. Pinning information

Table 2. Pinning

Pin	Description		Simplified outline	Graphic symbol
BLF6G10	0-200RN (SOT502A)			
1	drain			,
2	gate			1
3	source	<u>[1]</u>		2
				3 sym112
BLF6G10	0LS-200RN (SOT502B)			
1	drain			,
2	gate		1 3	1 1
3	source	<u>[1]</u>	2	2 —
				3 sym112

^[1] Connected to flange.

3. Ordering information

Table 3. Ordering information

Type number	Packag	ackage				
	Name	Description	Version			
BLF6G10-200RN	-	flanged LDMOST ceramic package; 2 mounting holes; 2 leads	SOT502A			
BLF6G10LS-200RN	-	earless flanged LDMOST ceramic package; 2 leads	SOT502B			

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage		-	65	V
V_{GS}	gate-source voltage		-0.5	+13	V
I_D	drain current		-	49	Α
T _{stg}	storage temperature		-65	+150	°C
T _j	junction temperature		-	225	°C

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Туре	Тур	Unit
R _{th(j-case)}	thermal resistance from	$T_{case} = 80 ^{\circ}C;$	BLF6G10-200RN	0.50	K/W
	junction to case	$P_L = 40 W$	BLF6G10LS-200RN	0.35	K/W

6. Characteristics

Table 6. Characteristics

 $T_i = 25$ °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 0.9 \text{ mA}$	65	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	V_{DS} = 10 V; I_{D} = 270 mA	1.4	2.0	2.4	V
V_{GSq}	gate-source quiescent voltage	$V_{DS} = 28 \text{ V};$ $I_D = 1620 \text{ mA}$	1.7	2.2	2.7	V
I _{DSS}	drain leakage current	$V_{GS} = 0 \text{ V}; V_{DS} = 28 \text{ V}$	-	-	4.2	μΑ
I _{DSX}	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 V;$ $V_{DS} = 10 V$	40	48	-	Α
I _{GSS}	gate leakage current	$V_{GS} = 11 \text{ V}; V_{DS} = 0 \text{ V}$	-	-	420	nA
9 _{fs}	forward transconductance	V_{DS} = 10 V; I_{D} = 9.45 A	11	18	26	S
R _{DS(on)}	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75 V;$ $I_D = 9.45 A$	0.012	0.07	0.093	Ω
C _{rs}	feedback capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 28 \text{ V};$ f = 1 MHz	-	3	-	pF

7. Application information

Table 7. Application information

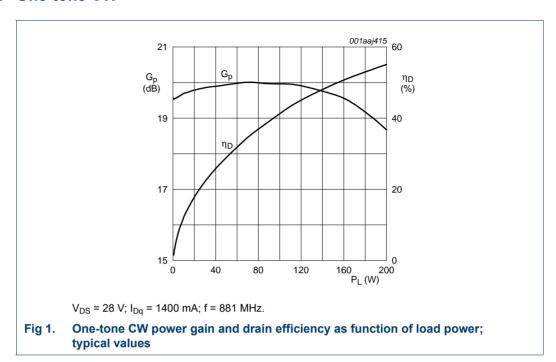
Mode of operation: 2-carrier W-CDMA; PAR 7.5 dB at 0.01 % probability on CCDF; 3GPP test model 1; 1-64 PDPCH; f_1 = 871.5 MHz; f_2 = 876.5 MHz; f_3 = 886.5 MHz; f_4 = 891.5 MHz; RF performance at V_{DS} = 28 V; I_{Dq} = 1400 mA; T_{case} = 25 °C; unless otherwise specified; in a class-AB production test circuit.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$P_{L(AV)}$	average output power		-	40	-	W
G_p	power gain	$P_{L(AV)} = 40 W$	19	20	-	dB
IRL	input return loss	$P_{L(AV)} = 40 \text{ W}$	-	-6.4	-4.5	dB
η_{D}	drain efficiency	$P_{L(AV)} = 40 \text{ W}$	25	28.5	-	%
ACPR	adjacent channel power ratio	$P_{L(AV)} = 40 \text{ W}$	-	-39.4	-36	dBc

7.1 Ruggedness in class-AB operation

The BLF6G10-200RN and BLF6G10LS-200RN are enhanced rugged devices and are capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions: V_{DS} = 28 V; I_{Dq} = 1400 mA; P_{L} = 200 W; f = 894 MHz.

7.2 One-tone CW



7.3 Two-tone CW

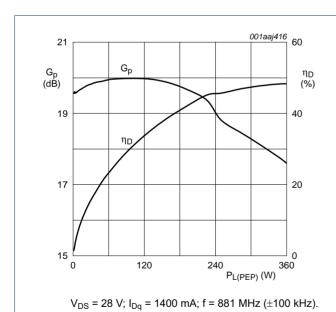
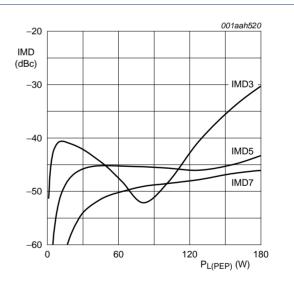


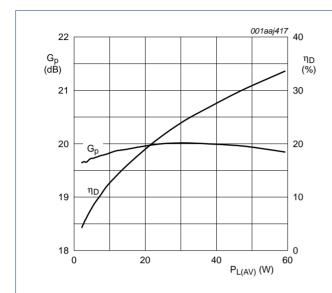
Fig 2. Two-tone CW power gain and drain efficiency as function of peak envelope load power; typical values



 V_{DS} = 28 V; I_{Dq} = 1400 mA; f = 881 MHz (±100 kHz).

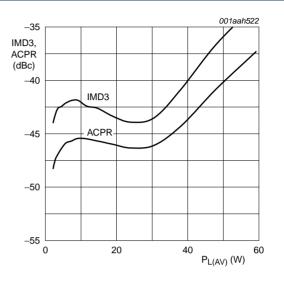
Fig 3. Two-tone CW intermodulation distortion as a function of peak envelope load power; typical values

7.4 2-carrier W-CDMA



 V_{DS} = 28 V; I_{Dq} = 1400 mA; f = 881 MHz (±5 MHz); carrier spacing 10 MHz.

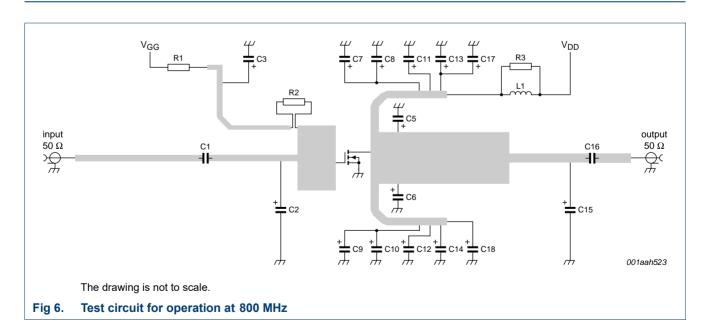
Fig 4. 2-carrier W-CDMA power gain and drain efficiency as function of average load power; typical values

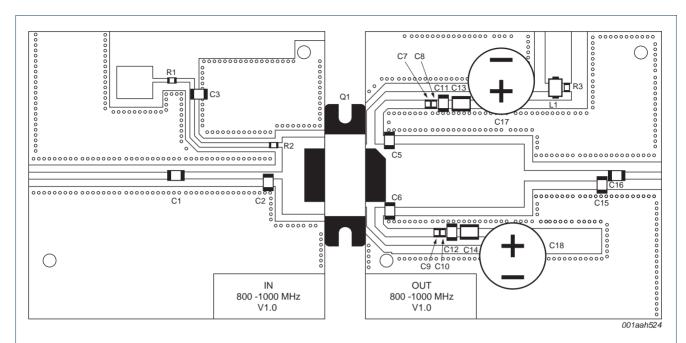


 V_{DS} = 28 V; I_{Dq} = 1400 mA; f = 881 MHz (\pm 5 MHz); carrier spacing 10 MHz.

Fig 5. 2-carrier W-CDMA adjacent channel power ratio and third order intermodulation distortion as function of average load power; typical values

8. Test information





The striplines are on a double copper-clad Taconic RF35 Printed-Circuit Board (PCB) with ϵ_r = 3.5 and thickness = 0.76 mm. See Table 8 for list of components.

The drawing is not to scale.

Fig 7. Component layout

Table 8. List of components See Figure 6 and Figure 7.

Component	Description	Value		Remarks
C1, C3, C11, C12, C16	multilayer ceramic chip capacitor	68 pF	[1]	solder vertically
C2	multilayer ceramic chip capacitor	13 pF	[1]	solder vertically
C5, C6	multilayer ceramic chip capacitor	10 pF	[1]	solder vertically
C7, C8, C9, C10	electrolytic capacitor	220 nF		Vishay VJ1206Y224KXB
C13, C14	multilayer ceramic chip capacitor	4.7 μF; 50 V	[2]	
C15	multilayer ceramic chip capacitor	1.5 pF	[1]	solder vertically
C17, C18	electrolytic capacitor	220 μF; 63 V		
L1	ferrite SMD bead	-		Ferroxcube BDS 3/3/4.6-4S2 or equivalent
Q1	BLF6G10LS-200RN	-		
R1, R2, R3	SMD resistor	9.1 Ω; 0.1 W		

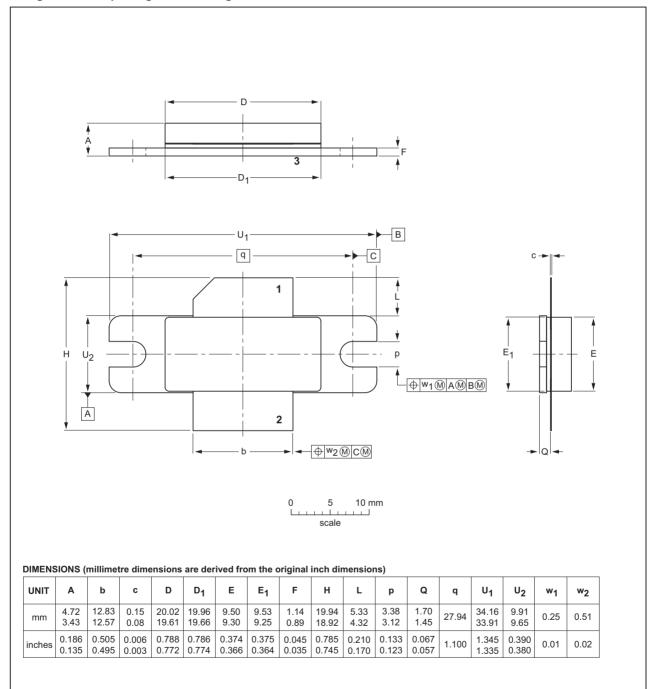
^[1] American Technical Ceramics type 100B or capacitor of same quality.

^[2] TDK or capacitor of same quality.

9. Package outline

Flanged ceramic package; 2 mounting holes; 2 leads

SOT502A



OUTLINE		REFERENCES			EUROPEAN ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT502A						-03-01-10- 12-05-02	

Fig 8. Package outline SOT502A

Earless flanged ceramic package; 2 leads

SOT502B

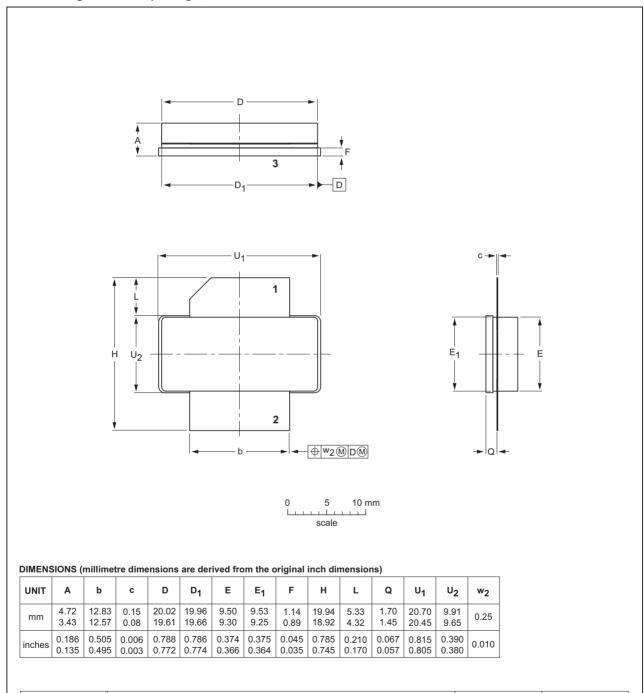


Fig 9. Package outline SOT502B

IEC

OUTLINE

VERSION

SOT502B

JEITA

REFERENCES

JEDEC

ISSUE DATE

07-05-09

12-05-02

EUROPEAN

PROJECTION

10. Abbreviations

Table 9. Abbreviations

Idolo J. Ak	701011410110
Acronym	Description
3GPP	Third Generation Partnership Project
CCDF	Complementary Cumulative Distribution Function
CDMA	Code Division Multiple Access
CW	Continuous Wave
DPCH	Dedicated Physical CHannel
EDGE	Enhanced Data rates for GSM Evolution
GSM	Global System for Mobile communications
LDMOS	Laterally Diffused Metal-Oxide Semiconductor
LDMOST	Laterally Diffused Metal-Oxide Semiconductor Transistor
PAR	Peak-to-Average power Ratio
PDPCH	transmission Power of the Dedicated Physical CHannel
RF	Radio Frequency
SMD	Surface Mounted Device
VSWR	Voltage Standing-Wave Ratio
W-CDMA	Wideband Code Division Multiple Access

11. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLF6G10-200RN_10LS-200RN#3	20150901	Product data sheet	-	BLF6G10-200RN_10LS-200RN_2
Modifications:	 The format of this document has been redesigned to comply with the new identity guidelines of Ampleon. 			
	Legal texts have been adapted to the new company name where appropriate.			
BLF6G10-200RN_10LS-200RN_2	20100121	Product data sheet	-	BLF6G10-200RN_10LS-200RN_1
BLF6G10-200RN_10LS-200RN_1	20090119	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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14. Contents

1	Product profile
1.1	General description
1.2	Features
1.3	Applications
2	Pinning information
3	Ordering information
4	Limiting values
5	Thermal characteristics 3
6	Characteristics 3
7	Application information
7.1	Ruggedness in class-AB operation 3
7.2	One-tone CW
7.3	Two-tone CW
7.4	2-carrier W-CDMA 5
8	Test information
9	Package outline
10	Abbreviations 9
11	Revision history
12	Legal information
12.1	Data sheet status
12.2	Definitions
12.3	Disclaimers
12.4	Trademarks10
13	Contact information
14	Contents 12

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